

LH51256L

CMOS 256K (32K × 8) Static RAM

FEATURES

- 32,768 × 8 bit organization
- Access times: 100/120 ns (MAX.)
- Power consumption:
Operating: 248 mW (MAX.)
(TA = -40 to 85°C, minimum cycle)
Standby: 5.5 µW (MAX.)
(TA = 0 to 60°C)
- Fully-static operation
- TTL compatible I/O
- Three-state outputs
- Single +5 V power supply
- Packages:
28-pin, 600-mil DIP
28-pin, 450-mil SOP

DESCRIPTION

The LH51256L is a 256K bit static RAM organized as 32,768 × 8 bits which provides low-power standby mode. It is fabricated using silicon-gate CMOS process technology.

PIN CONNECTIONS

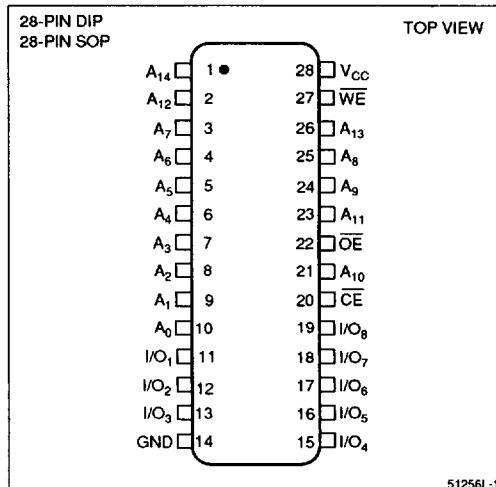


Figure 1. Pin Connections for DIP and SOP Packages

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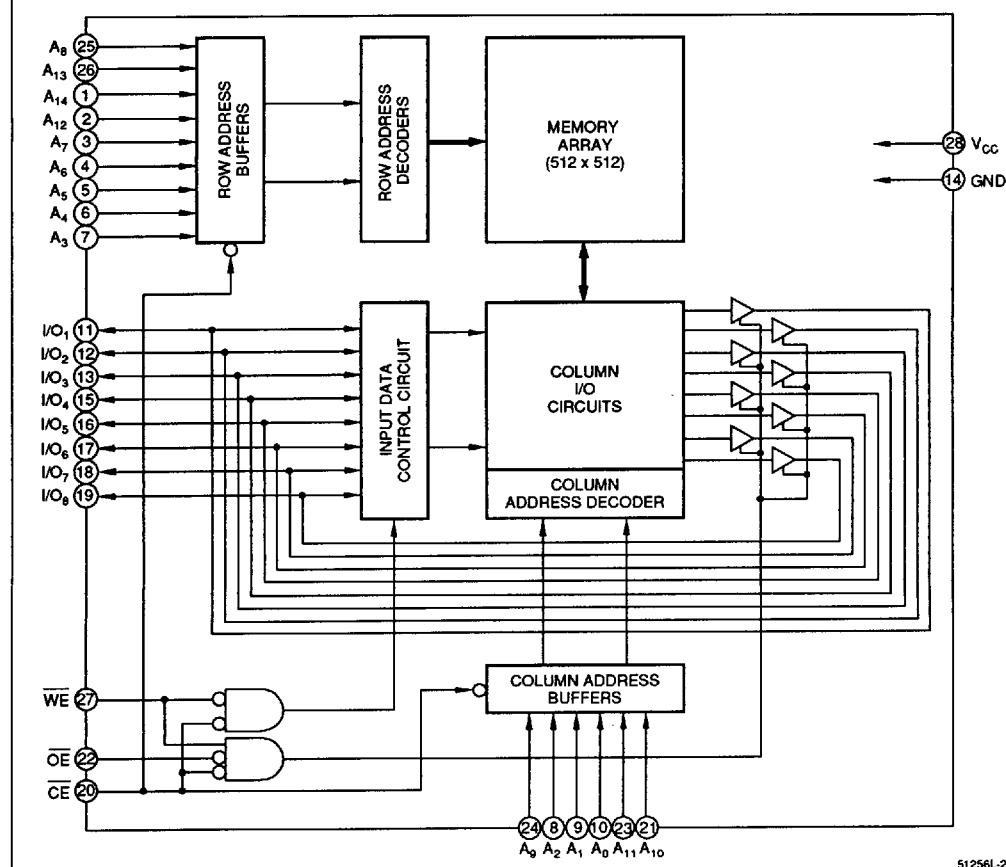


Figure 2. LH51256L Block Diagram

PIN DESCRIPTION

SIGNAL	PIN NAME
$A_0 - A_{14}$	Address input
\overline{CE}	Chip Enable input
WE	Write Enable input
\overline{OE}	Output Enable input

SIGNAL	PIN NAME
$I/O_1 - I/O_8$	Data Input/Output
V_{CC}	Power supply
GND	Ground

TRUTH TABLE

\overline{CE}	WE	\overline{OE}	MODE	$I/O_1 - I/O_8$	SUPPLY CURRENT	NOTE
H	X	X	Non selected	High-Z	Standby (I_{SS})	1
L	L	X	Write	D _{IN}	Operating (I_{CC})	1
L	H	L	Read	D _{OUT}	Operating (I_{CC})	
L	H	H	Output disable	High-Z	Operating (I_{CC})	

NOTE:

1. X = H or L

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	RATING	UNIT	NOTE
Supply voltage	V _{CC}	-0.3 to +7.0	V	1
Input voltage	V _{IN}	-0.3 to +7.0	V	1
Operating temperature	T _{opr}	-40 to +85	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

NOTE:

1. The maximum applicable voltage on any pin with respect to GND.

RECOMMENDED OPERATING CONDITIONS (T_A = -40 to +85°C)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply voltage	V _{CC}	4.5	5.0	5.5	V
Input voltage	V _{IH}	2.2		V _{CC} + 0.3	V
	V _{IL}	-0.3		0.8	V

DC CHARACTERISTICS (V_{CC} = 5 V ± 10%, T_A = -40 to +85°C)

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Input leakage current	I _{LI}	V _{CC} = 5.5 V V _{IN} = 0 to V _{CC}			1	µA
Output leakage current	I _{LO}	CE or OE = V _{IH} , V _{IO} = 0 to V _{CC}			1	µA
Operating current	I _{CC}	CE = V _{IL} , Outputs open			45	mA
	I _{SB1}	CE = V _{IH}			10	mA
Standby current	I _{SB}	CE ≥ V _{CC} - 0.2 V T _A = 0 to +60°C			1	µA
		CE ≥ V _{CC} - 0.2 V T _A = -40 to +85°C			5	µA
Output voltage	V _{OL}	I _{OL} = 2.1 mA			0.4	V
	V _{OH}	I _{OH} = -1.0 mA	2.4			V

AC CHARACTERISTICS**(1) READ CYCLE (V_{CC} = 5 V ± 10%, T_A = -40 to +85°C)**

PARAMETER	SYMBOL	LH51256/N-10L		LH51256/N-12L		UNIT	NOTE
		MIN.	MAX.	MIN.	MAX.		
Read cycle time	t _{RC}	100		120		ns	
Address access time	t _{AA}		100		120	ns	
Chip enable access time	t _{ACE}		100		120	ns	
Output enable access time	t _{OE}		50		60	ns	
Output hold time	t _{OH}	5		5		ns	
CE Low to output in Low-Z	t _{LZ}	5		5		ns	1
OE Low to output in Low-Z	t _{OLZ}	5		5		ns	1
CE High to output in High-Z	t _{HZ}	0	30	0	30	ns	1
OE High to output in High-Z	t _{OHz}	0	30	0	30	ns	1

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(2) WRITE CYCLE (V_{CC} = 5 V ± 10%, T_A = -40 to +85°C)

PARAMETER	SYMBOL	LH51256/N-10L		LH51256/N-12L		UNIT	NOTE
		MIN.	MAX.	MIN.	MAX.		
Write cycle time	t _{WC}	100		120		ns	
CE Low to end of write	t _{CW}	90		100		ns	
Address valid to end of write	t _{AW}	90		100		ns	
Address setup time	t _{AS}	5		5		ns	
Write recovery time	t _{WR}	15		15		ns	
Write pulse width	t _{WP}	50		50		ns	
Input data setup time	t _{DW}	30		30		ns	
Input data hold time	t _{DH}	10		10		ns	
WE High to output in High-Z	t _{OW}	0		0		ns	1
WE Low to output in High-Z	t _{WZ}	0	30	0	30	ns	1
OE High to output in High-Z	t _{OHZ}	0	30	0	30	ns	1

NOTE:

1. Active output to high-impedance and high-impedance to output active tests specified for a ±500 mV transition from steady state levels into the test load. C_{LOAD} = 5 pF.

AC TEST CONDITIONS

PARAMETER	MODE
Input voltage amplitude	0.6 V to 2.4 V
Input rise/fall time	10 ns
Timing reference level	1.5 V
Output load conditions	1 TTL + C _L = 100 pF (Includes scope and jig capacitance)

CAPACITANCE¹ (T_A = 25°C, f = 1MHz)

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Input capacitance	C _{IN}	V _{IN} = 0 V			7	pF
Input/output capacitance	C _{I/O}	V _{I/O} = 0 V			10	pF

NOTE:

1. This parameter is sampled and not production tested.

DATA RETENTION CHARACTERISTICS (T_A = -40 TO +85°C)

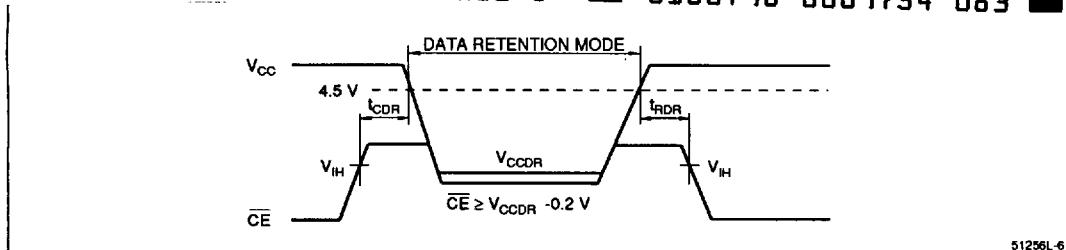
PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNIT	NOTE
Data retention voltage	V _{CCDR}	CE ≥ V _{CCDR} - 0.2 V	2.0			V	
Data retention current	I _{CCDR}	V _{CCDR} = 3.0 V, CE ≥ V _{CCDR} - 0.2 V, T _A = 0 to +60°C, V _{IN} = 0 to V _{CCDR}			0.6	μA	
		V _{CCDR} = 3.0 V CE ≥ V _{CCDR} - 0.2 V, T _A = -40 to +85°C, V _{IN} = 0 to V _{CCDR}			3.0	μA	
CE setup time	t _{CDR}		0			ns	
CE hold time	t _{RDR}		t _{RC}			ns	1

NOTE:

1. t_{RC} = Read cycle time

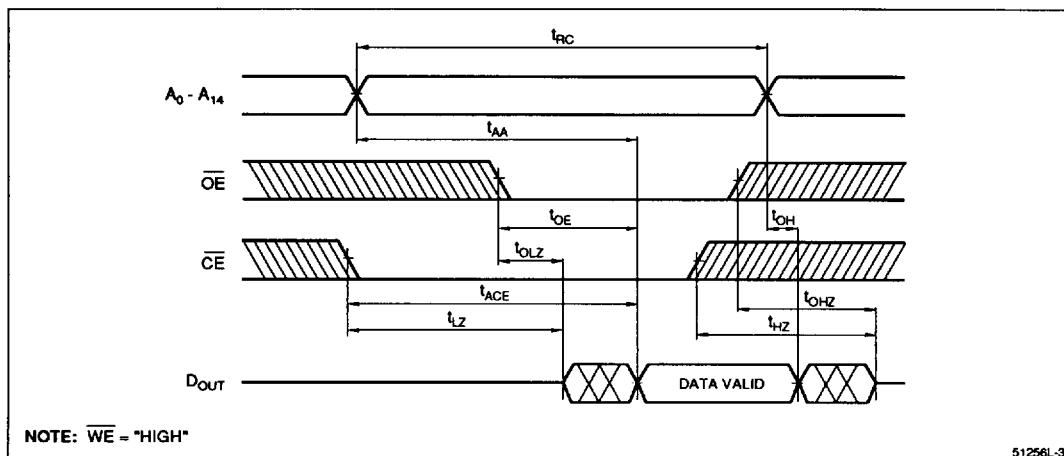
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Figure 3. Data Retention Characteristics

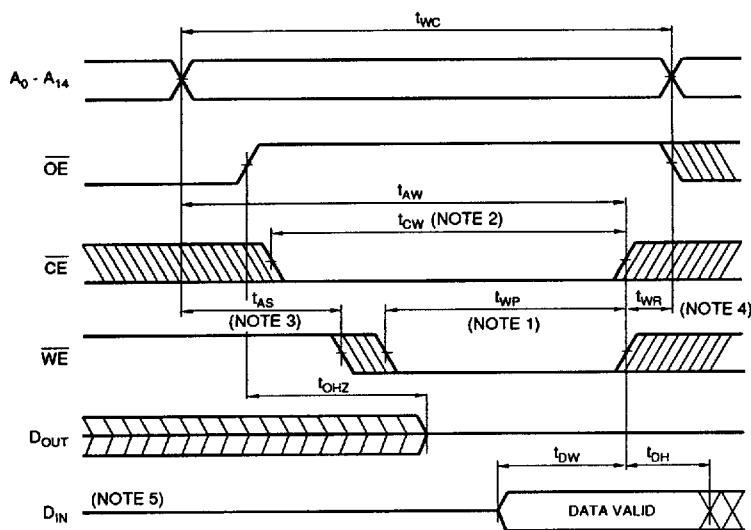


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Figure 4. Read Cycle

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**NOTES:**

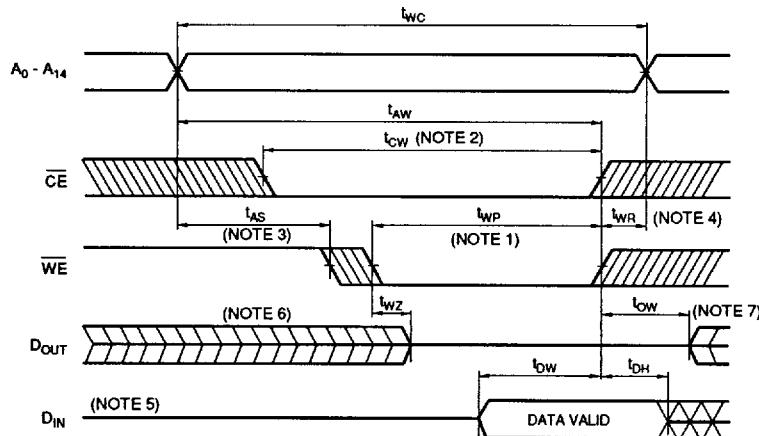
1. The write pulse occurs during the overlap (t_{WP}) of $\overline{CE} = \text{LOW}$ and $\overline{WE} = \text{LOW}$.
2. t_{CW} is defined as the time from \overline{CE} LOW transition to the end of writing.
3. t_{AS} is defined as the time from address change to the start of writing.
4. t_{WR} is defined as the time from the end of writing to the address change.
5. When the I/O pins are in the output state, input signals with the opposite logic level must not be applied.

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Figure 5. Write Cycle 1 (OE Clock)

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**NOTES:**

1. The write pulse occurs during the overlap (t_{wp}) of $\overline{CE} = \text{LOW}$ and $\overline{WE} = \text{LOW}$.
2. t_{cw} is defined as the time from $CE = \text{LOW}$ transition to the end of writing.
3. t_{as} is defined as the time from address change to the start of writing.
4. t_{wr} is defined as the time from the end of writing to the address change.
5. When the I/O pins are in the output state, input signals with the opposite logic level must not be applied.
6. If $CE = \text{LOW}$ transition occurs at the same time or after $WE = \text{LOW}$ transition, the output will remain high-impedance.
7. If $CE = \text{HIGH}$ transition occurs at the same time or prior to the $WE = \text{HIGH}$ transition, the output will remain high-impedance.

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Figure 6. Write Cycle 2 (OE Low)

ORDERING INFORMATION

LH51256	X	- ##	Speed
Device Type	Package		
			{ 10L 100 12L 120 Access Time (ns)
			{ Blank 28-pin, 600-mil DIP (DIP28-P-600) N 28-pin, 450-mil SOP (SOP28-P-450)
CMOS 256K (32K × 8) Static RAM, Low-power standby			

Example: LH51256N-10L (CMOS 256K (32K × 8) Static RAM, 100 ns, 28-pin, 450-mil SOP)

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